



Material Content Data Sheet



Sales Product Name				IPD400N06N G		Issued		1. August 2018	
MA#				MA000446614					
Package				PG-TO252-3-311		Weight*		313.33 mg	
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]	
chip	inorganic material	silicon	7440-21-3	1.550	0.49	0.49	4948	4948	
leadframe	inorganic material	phosphorus	7723-14-0	0.043	0.01		137		
	non noble metal	iron	7439-89-6	0.143	0.05		457		
	non noble metal	copper	7440-50-8	143.098	45.68	45.74	456705	457299	
	non noble metal	aluminium	7429-90-5	1.035	0.33	0.33	3304	3304	
wire	inorganic material	antimonytrioxide	1309-64-4	2.000	0.64		6382		
encapsulation	plastics	brominated resin	-	2.142	0.68		6838		
	organic material	carbon black	1333-86-4	2.285	0.73		7294		
	plastics	epoxy resin	-	19.282	6.15		61539		
	inorganic material	silicondioxide	60676-86-0	117.121	37.38	45.58	373794	455847	
leadfinish	non noble metal	tin	7440-31-5	3.740	1.19	1.19	11936	11936	
plating	inorganic material	phosphorus	7723-14-0	0.000	0.00		1		
	non noble metal	nickel	7440-02-0	0.086	0.03	0.03	276	277	
solder	non noble metal	tin	7440-31-5	0.032	0.01		102		
	noble metal	silver	7440-22-4	0.040	0.01		128		
	non noble metal	lead	7439-92-1	1.528	0.49	0.51	4875	5105	
heatspreader	inorganic material	phosphorus	7723-14-0	0.006	0.00		18		
	non noble metal	iron	7439-89-6	0.019	0.01		61		
	non noble metal	copper	7440-50-8	19.177	6.12	6.13	61205	61284	
*deviation	< 10%		Sum in total:			100.00		1000000	

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

Company	Infineon Technologies AG
Address	81726 München
Internet	www.infineon.com